


**TRANSMITTAL**

Electronic Version v1.1

Stylesheet Version v1.1.0

<b>Title of Invention</b>	Method and Apparatus for Using Connection Graphs with Potential Diagonal Edges to Model Interconnect Topologies During Placement	
Application Number :	09/737245	
Date :	2000-12-13	
First Named Applicant:	Teig, et al. Steven	
Confirmation Number:	8353	
Attorney Docket Number:	SPLX.P0012	
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Documents being submitted:	Files
us-fee-sheet	SPLX.P0012-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
us-ids	SPLX.P0012-usidst.xml us-ids.dtd us-ids.xsl
<b>Comments</b>	
This is the first eIDS submission of two total eIDS submissions for application number 09/737,245.	